

PART NO.
20032-...U-#4

☆EXAMPLE 20032-...*-#4

* MARK MEANS PACKAGE STYLE

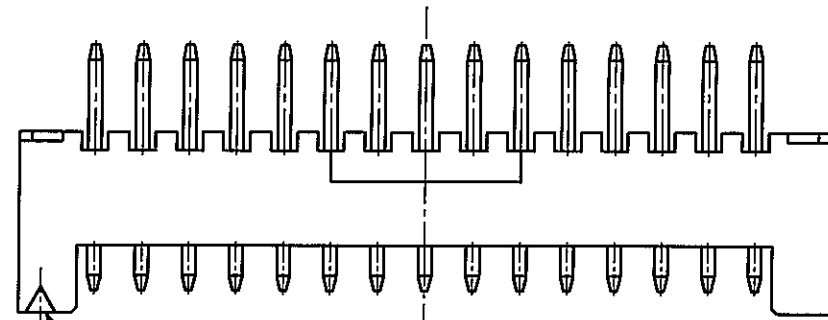
U : TUBE PACKAGE
B : BAG PACKAGE

MARK MEANS FINISH

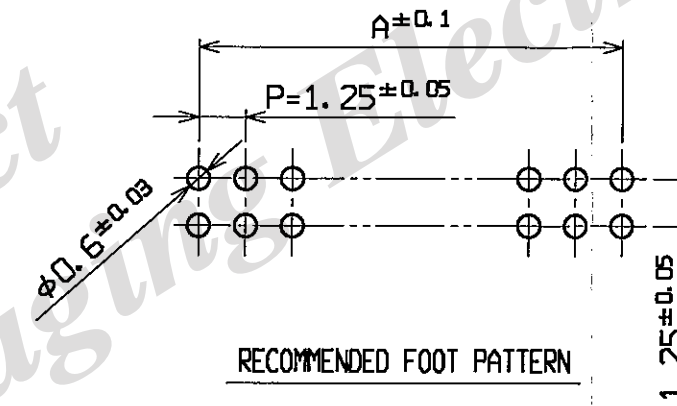
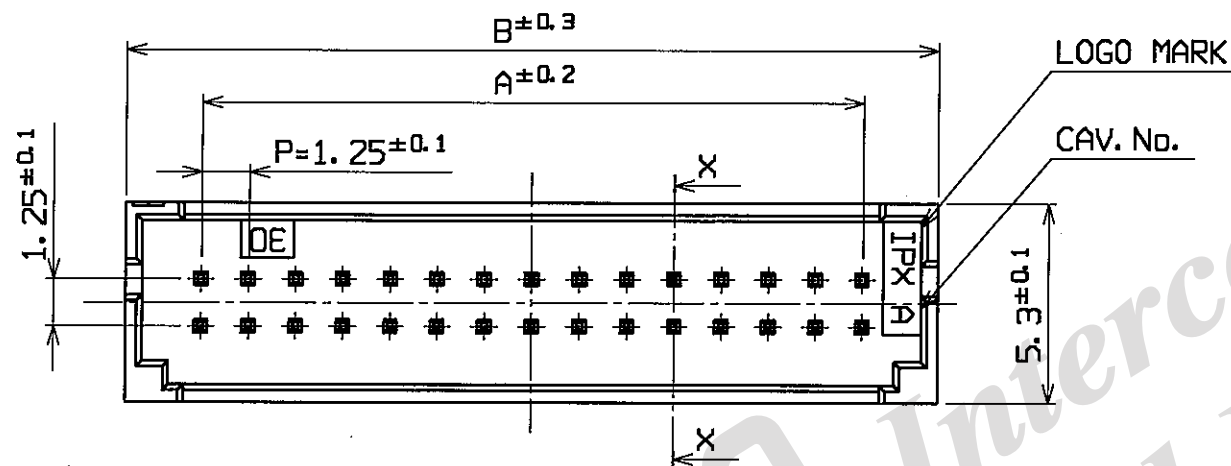
0 : Sn-Pb OVER NI
1 : Au OVER NI

PART. NO.	POS.	A	B
◆ 20032-010*-#4	10	5.0	9.0
20032-020*-#4	20	11.25	15.25
20032-022*-#4	22	12.5	16.5
◆ 20032-030*-#4	30	17.5	21.5
◆ 20032-032*-#4	32	18.75	22.75
20032-040*-#4	40	23.75	27.75
◆ 20032-042*-#4	42	25.0	29.0
◆ 20032-050*-#4	50	30.0	34.0

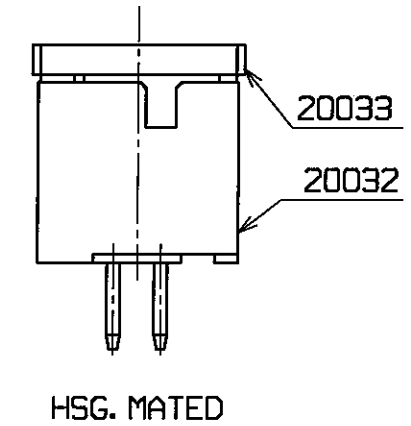
◆ MARK MEANS UNDER DEVELOPPING.



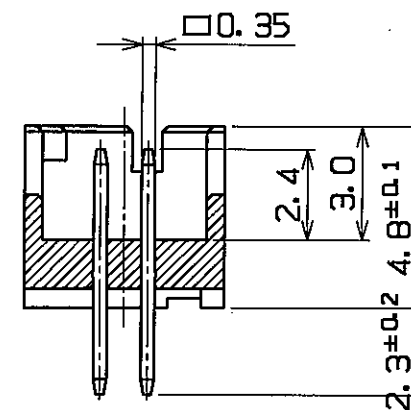
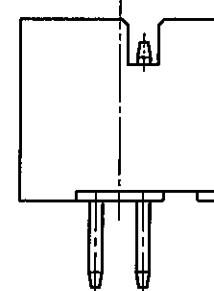
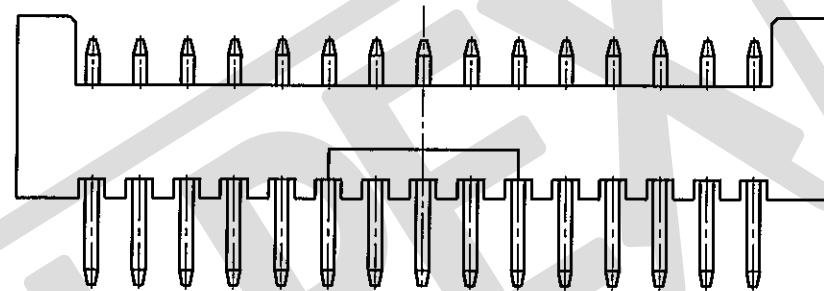
DATUM PIN MARK



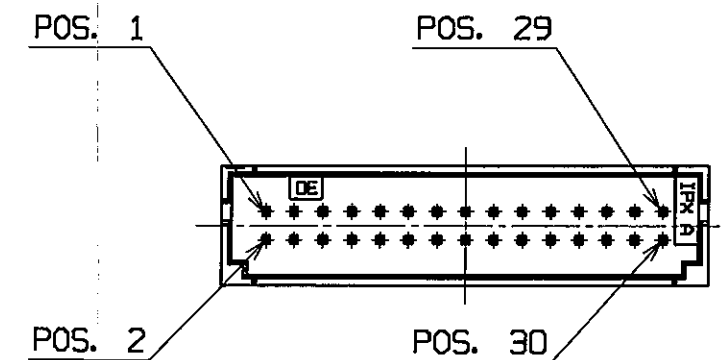
RECOMMENDED FOOT PATTERN



HSG. MATED



SECT. X-X



POS. NO. EX. : 30P

NOTES

- MATERIAL & FINISH
INSULATOR - PA66(UL94V-0)
CONTACT (STANDARD) - COPPER ALLOY
Sn-Pb OVER NI (UNDER 30 PINS)
Au OVER NI (30 PINS OR OVER)
- P/N 20032-...U-04, 20032-...U-14: SEE 300-040 OF THE PACKING STANDARD.
P/N 20032-...B-04, 20032-...B-14: SEE 300-069 OF THE PACKING STANDARD.

REV	ECN	BY	DATE	CHK	SERIES No.	2210
7	D6081	J. T	07/04/96	Y. F	DESIGN'D BY	DATE
6	D6078	T. T	07/01/96	Y. F	M. TSURUSAKI	01/12/96
5	D6062	J. T	06/10/96	Y. F	CHK'D BY	DATE
4	D6052	J. T	05/30/96	Y. F	Y. H	02/06/96
3	D6024	T. T	03/29/96	Y. F	APP'D BY	DATE
9	D7076	T. T	10/16/97	Y. F	Y. F	02/16/96
8	D6108	T. M	09/18/96	Y. F	Y. F	02/16/96

I-PEX Interconnect and Packaging Electronics TOKYO, JAPAN

TOL. ±0.3, ±2'

TITLE DUALOK DUAL TYPE HDR ASS'Y ST-TMT

SCALE 5/1 UNIT mm

DWG. No. 20032 SHEET 1/1 REV. 9

CUSTOMER COPY

PROJECTION